

Title of Change:	Change in Packing Method for Flat Ring devices
Effective date:	31 Aug 2022
Contact information:	Contact your local onsemi Sales Office or Jam.Castillo@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Assembly Change
Change Sub-Category(s):	Manufacturing Process Change

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Tarlac, Philippines	None

Description and Purpose:

The current packing material used for flat ring packages, which is the PP board, is no longer available. A new packing material (wafer canister) has been qualified to replace the PP board.

	From	To
Packing Method	<p>PP Board</p>	<p>Wafer Canister</p>

There are no product material changes as a result of this change

There is no product marking change as a result of this change

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

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